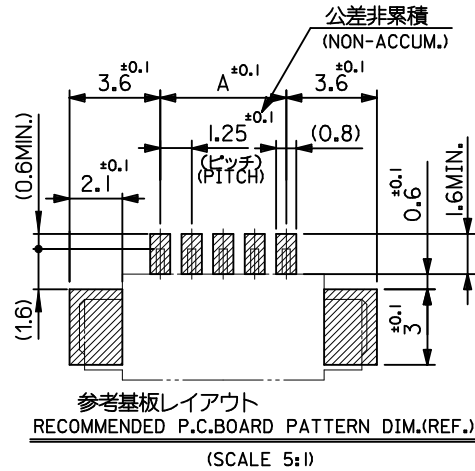
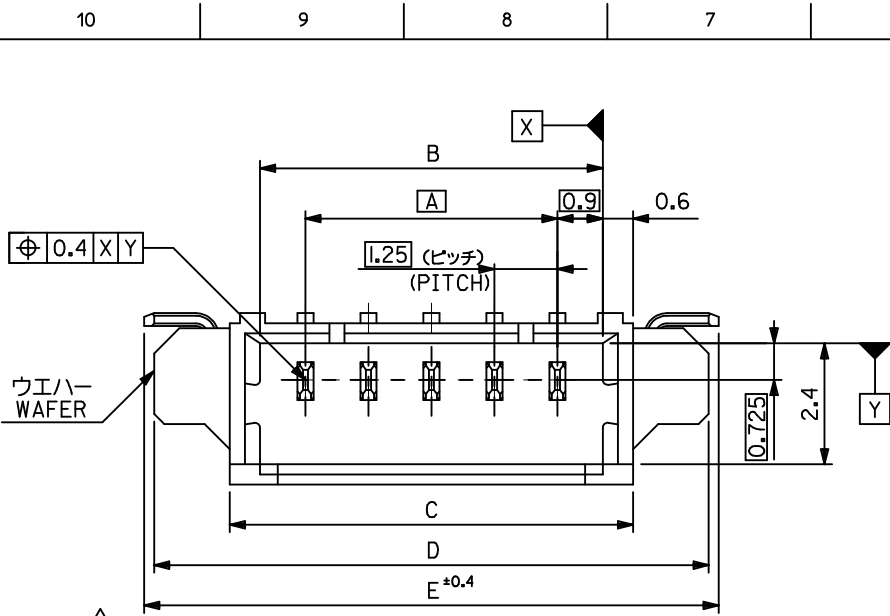




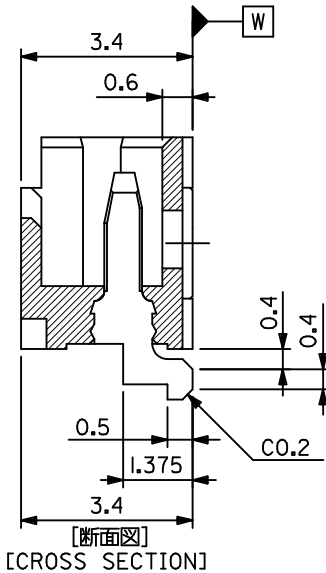
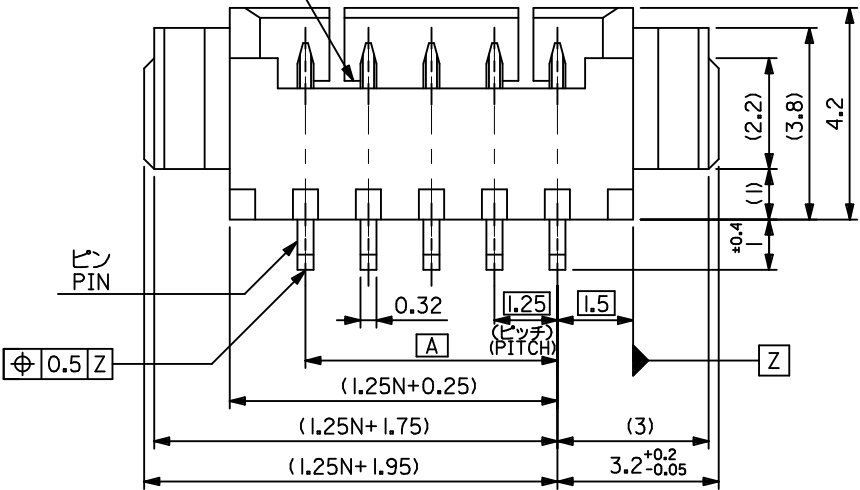
THE DATASHEET OF
53261-1090



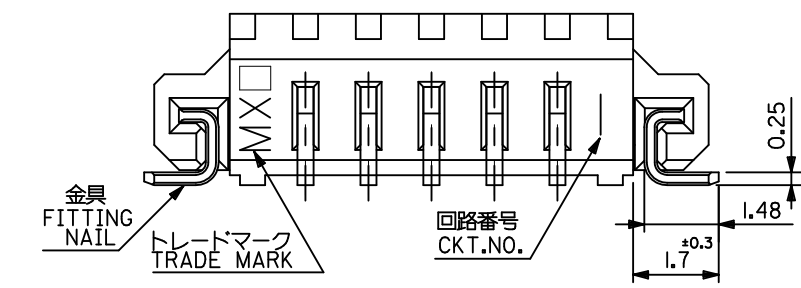


注記 NOTES

1. 嵌合相手: 51021 シリーズ
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅, 半田メッキ
PIN: PHOS-BRO., Sn-Pb(9:1) 3 μmMIN.
OVER Cu 1 μmMIN.
PLATING
金具: リン青銅, 半田メッキ
FITTING NAIL: PHOS-BRO., Sn-Pb(9:1) 2 μmMIN.
OVER Cu 1 μmMIN.
PLATING
- △ ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダータール部のズレ量及び金具(補強板)のズレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM: UPPER SIDE: 0.05MAX. LOWER SIDE: 0.1MAX.

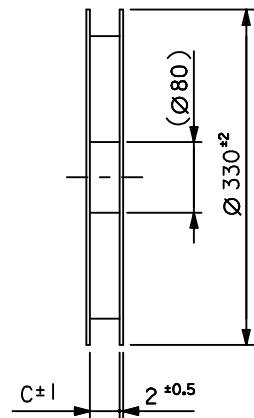
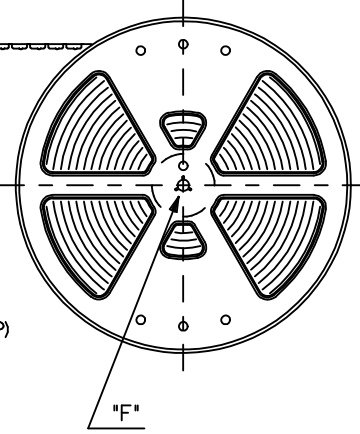


23.9	23.5	20.5	19.3	17.5	53261-1510	15
22.65	22.25	19.25	18.05	16.25	-1410	14
21.4	21	18	16.8	15	-1310	13
20.15	19.75	16.75	15.55	13.75	-1210	12
18.9	18.5	15.5	14.3	12.5	-1110	11
17.65	17.25	14.25	13.05	11.25	-1010	10
16.4	16	13	11.8	10	-0910	9
15.15	14.75	11.75	10.55	8.75	-0810	8
13.9	13.5	10.5	9.3	7.5	-0710	7
12.65	12.25	9.25	8.05	6.25	-0610	6
11.4	11	8	6.8	5	-0510	5
10.15	9.75	6.75	5.55	3.75	-0410	4
8.9	8.5	5.5	4.3	2.5	-0310	3
7.65	7.25	4.25	3.05	1.25	53261-0210	2
E	D	C	B	A	ENG. NO.	極数 CKT.



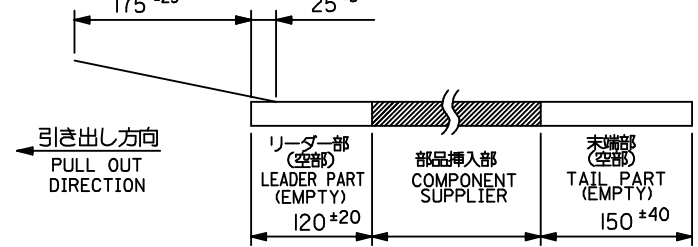
REVISED EC NO: J2012-1315 2012/04/17 DRWN: NITO 2012/04/17 CHKD: KASAKAWA 2012/04/17 APPR: YOITO 2012/04/26	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
		10 UNDER ±0.2		MM ONLY		10:1		METRIC		◎ □	
		10 OVER 30 UNDER ±0.25		DRAWN BY DATE		TITLE		1.25 WIRE TO BOARD WAFER ASS FOR SMT RIGHT ANGLE		molex	
		30 OVER ±0.3		NITO 2012/04/17		SEE DRAWING					
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
				SEE DRAWING		SD-53261-054		1 OF 1			
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

引き出し方向
PULL OUT DIRECTION



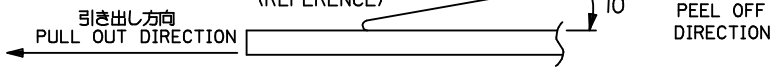
注記
NOTES

- 53261-**-10 の詳細寸法については図面 SD-53261-**-10 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-**-10.
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダ部 TOP TAPE LEADER PART 175 ± 25
トップテープ未接着部 TOP TAPE NON-BONDED PART 25 ± 5



- トップテープの剥離強度: 0.1N ~ 0.59N (10.2 ~ 60gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.1N ~ 0.59N (10.2 ~ 60gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

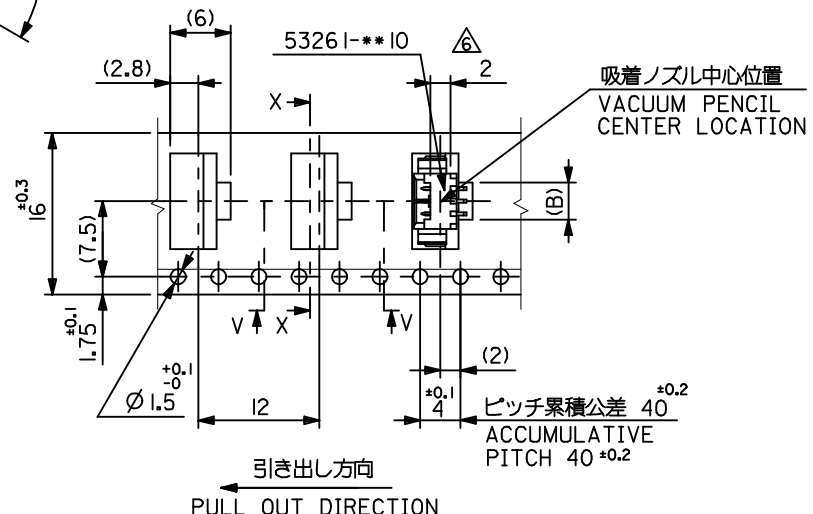
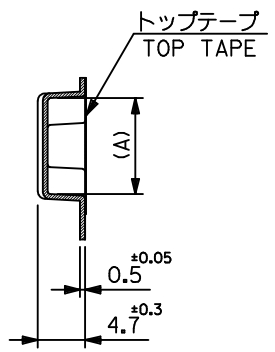
<剥離速度: 300mm/min (参考)>
PEELING SPEED: 300mm/min. (REFERENCE)



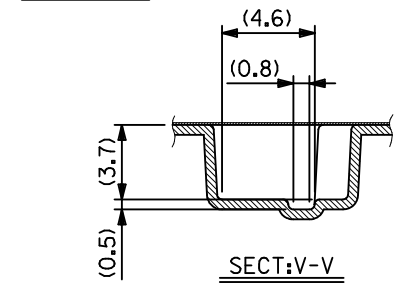
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

DETAIL "F"



SECT:X-X

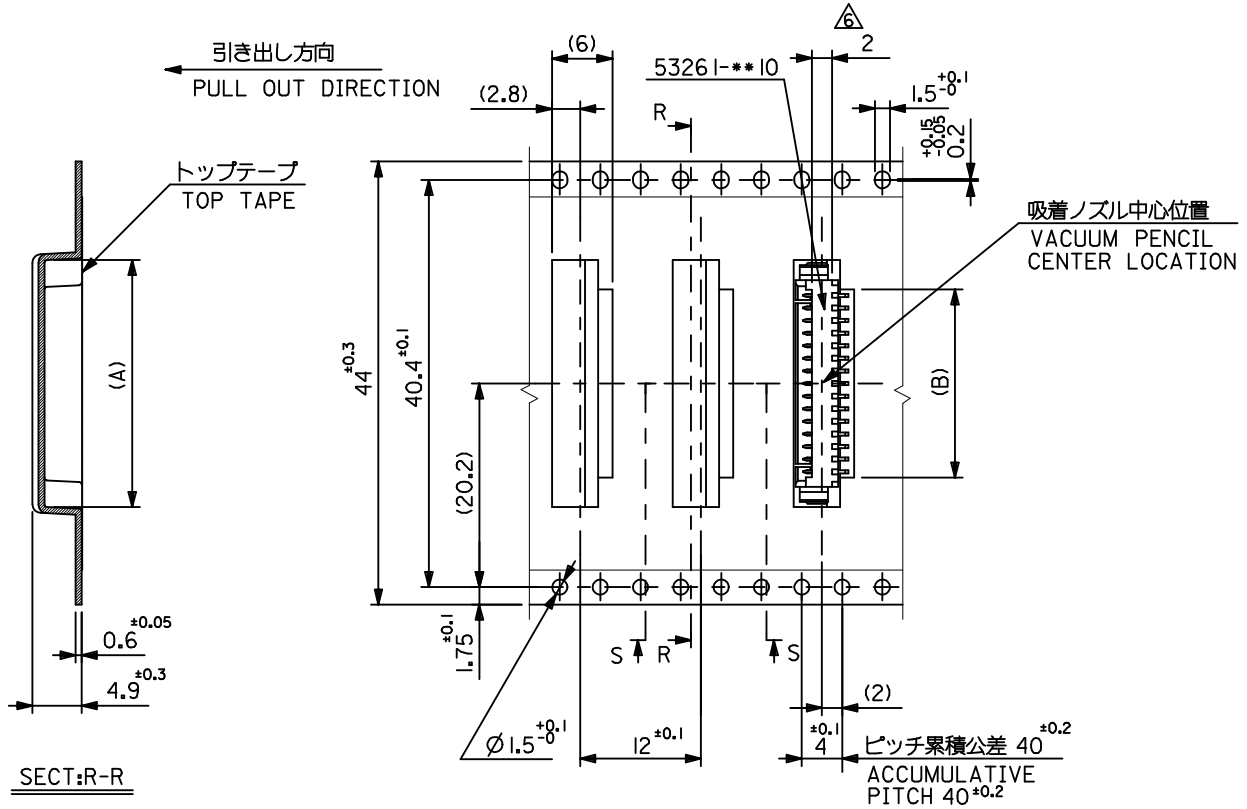


SECT:V-V

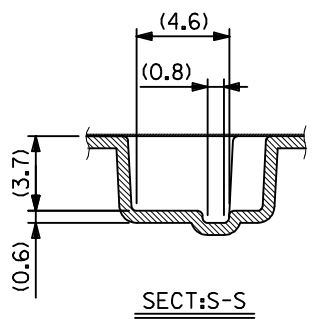
16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	16.4	3.7	9.5	53261-0390	3
		2.45	8.25	53261-0290	2
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	極数 CKT.

REVISED EC NO: J2014-1616 DRWN: TYAJIMA01 2014/04/28 CHKD: KASAKAWA 2014/04/28 APPR: NUKITA 2014/04/30	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY TYAJIMA01	DATE 2014/04/28	TITLE 1.25 W/B CONN. WAFER ASSY FOR SMT. EMBOSSED TAPE PACKAGE			
		10 OVER 30 UNDER	± ---	CHECKED BY KASAKAWA	DATE 2014/04/28				
		30 OVER	± ---	APPROVED BY	DATE				
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE NOTES		DOCUMENT NO. SD-53261-055		SHEET NO. 1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



SECT:R-R



SECT:S-S

44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

44	44.4	18.7	24.5	53261-I590	15
		17.45	23.25	53261-I490	14
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	種数 CKT.

REVISED EC NO: J2014-1616 DRWN: TYAJIMA01 2014/04/28 CHKD: KASAKAWA 2014/04/28 APPR: NUKITA 2014/04/30	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY TYAJIMA01	DATE 2014/04/28	TITLE 1.25 W/B CONN. WAFER ASSY FOR SMT. EMBOSSED TAPE PACKAGE				
		10 OVER 30 UNDER	± ---	CHECKED BY KASAKAWA	DATE 2014/04/28					
		30 OVER	± ---	APPROVED BY NUKITA	DATE 2014/04/30					
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE NOTES		DOCUMENT NO. SD-53261-055		SHEET NO. 3 OF 3		

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